

### **Surface Mount General Purpose Silicon Rectifiers**

Reverse Voltage - 50 to 1000 V

Forward Current - 1 A

#### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



#### **Maximum Ratings and Electrical characteristics**

Ratings at  $25^{\circ}$ C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	S1AW	S1BW	S1DW	S1GW	S1JW	S1KW	S1MW	Units
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	٧
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	٧
Maximum Average Forward Rectified Current at Ta = 65 °C	I <sub>F(AV)</sub>	1						Α	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	25						Α	
Maximum Instantaneous Forward Voltage at 1 A	V <sub>F</sub>	1.1							٧
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta = 125 °C	I <sub>R</sub>	5 50						μА	
Typical Junction Capacitance 1)	Cj	4						pF	
Typical Thermal Resistance <sup>2)</sup>	R <sub>eJA</sub>	180						°C/W	
Operating and Storage Temperature Range	$T_{j}, T_{stg}$	-55 ~ <b>+</b> 150							°C

1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

2) Thermal resistance from junction to ambient at 0.375" (9.5 mm) lead length, P.C.B. mounted

REV.08



Fig.1 Forward Current Derating Curve

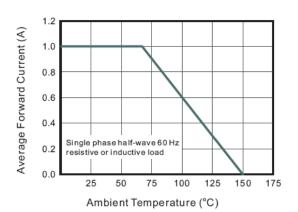


Fig.2 Typical Instaneous Reverse Characteristics

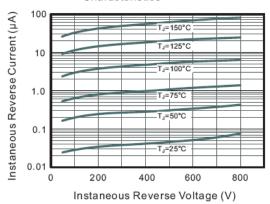


Fig.3 Typical Forward Characteristic

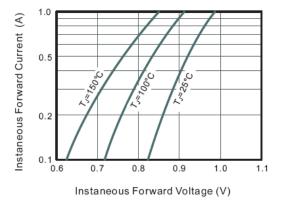
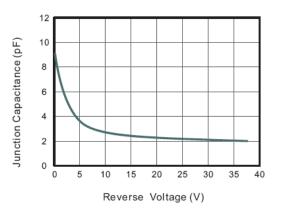


Fig.4 Typical Junction Capacitance

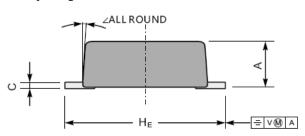


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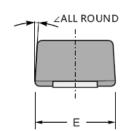


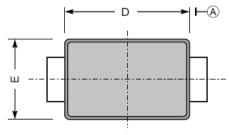
#### PACKAGE OUTLINE

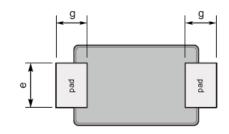
Plastic surface mounted package; 2 leads









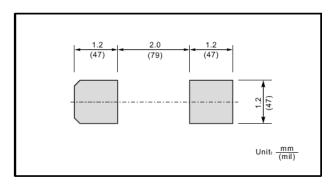


Top View

Bottom View

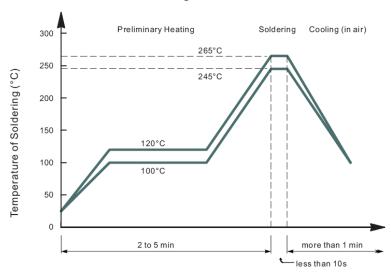
UNIT		Α	С	D	E	е	g	HE	_
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	7°
mil	max	43	7.9	114	75	43	35	150	,
	min	35	4.7	102	67	31	28	138	

#### The recommended mounting pad size

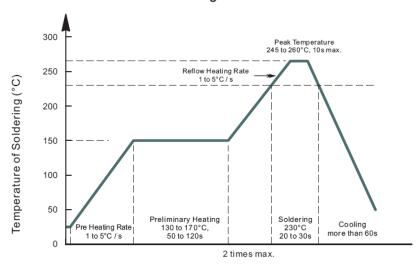




#### · Recommended condition of flow soldering



#### · Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)

• Condition of hand soldering

Temperature: 370°C

Time: 3s max.
Times: one time

• Remark:

Lead free solder paste (96.5Sn/3.0Ag/0.5Cu)

### 单击下面可查看定价,库存,交付和生命周期等信息

>>SHIKUES(时科)